

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant(s): Boldizar et al.	
Application No.: 10/788,951	Art Unit: 1733
Filed: 2/27/2004	Examiner: Jessica L. Rossi
Title: METHOD OF FORMING A LAYERED POLISHING PAD	
Attorney Docket No.: 02025US	

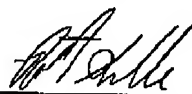
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

**DECLARATION UNDER 37 C.F.R. § 1.132**

That I Robert Gamble declare the following:

- 1) That I have been employed by Rohm and Haas Electronic Materials CMP Inc. (fka Rodel, Inc.) for eleven years.
- 2) That I have a B.S. degree in mechanical engineering from Temple University in 2001.
- 3) That I am a co-inventor of U.S. Ser. No. 10/788,951, entitled Method of Forming a Layered Polishing Pad filed February 27, 2004.
- 4) That applying a single layer of pressure sensitive adhesive ("PSA") to a polishing pad's subpad requires careful control to avoid curling and wrinkling of the subpad; and that curling or wrinkling of the subpad renders the polishing pad unacceptable.
- 5) That Rodel for several years used a first layer of PSA to attach the subpad to the polishing pad and then applied a second layer of PSA to the subpad to limit curling or wrinkling of the subpad.

- 6) That at the time of the invention, it was industry knowledge to apply the first layer of PSA between the pad and subpad to limit wrinkling.
- 7) That in approaching industry PSA experts from a major PSA supplier, the experts from the PSA supplier indicated that it would be "impossible" to apply PSA to both sides of a subpad for roll goods before attachment to a polishing pad because of curling issues.
- 8) That the inventors discovered that controlling nip exit angle  $\gamma$  to 0 degrees  $\pm$  3 degrees over a travel length limited curling of the double laminated subpad.
- 9) That I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.



Robert Gamble  
August 21, 2006